SR320 THRU SR3100

3.0 AMP SCHOTTKY BARRIER RECTIFIERS



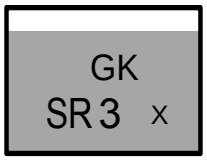
VOLTAGE RANGE
20 to 100 Volts
CURRENT
3.0 Ampere

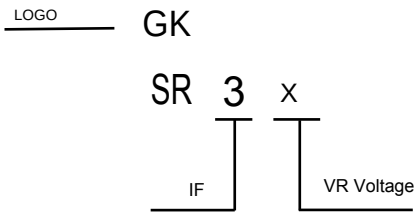
FEATURES

* Low forward voltage drop
* High current capability
* High reliability
* High surge current capability
* Epitaxial construction

MECHANICAL DATA

* Case: Molded plastic
* Epoxy: UL 94V-0 rate flame retardant
* Lead: Axial leads, solderable per MIL-STD-202, method 208 guranteed
* Polarity: Color band denotes cathode end
* Mounting position: Any
* Weight: 1.10 grams





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25℃ ambient temperature uniess otherwies specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	SR320	SR330	SR340	SR350	SR360	SR380	SR3100	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	100	V
Maximum RMS Voltage	14	21	28	35	42	56	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	100	V
Maximum Average Forward Rectified Current See Fig. 1	3.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	80							A
Maximum Instantaneous Forward Voltage at 3.0A	0.55			0.70		0.85		V
Maximum DC Reverse Current Ta=25℃	0.1					0.02		mA
at Rated DC Blocking Voltage Ta=100℃	5					2		mA
Typical Junction Capacitance (Note1)	300			250				pF
Typical Thermal Resistance R JA (Note 2)	20			10				℃/W
Operating Temperature Range TJ	-65 —+150							℃
Storage Temperature Range TSTG	-65 — +150							℃

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. Thermal Resistance Junction to Ambient Vertical PC Board Mounting 0.5"(12.7mm) Lead Length.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

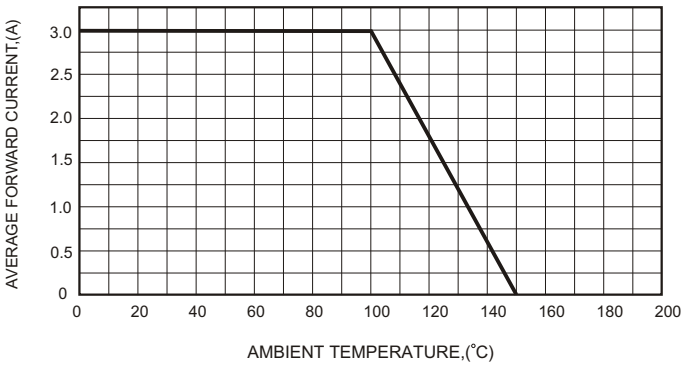


FIG.2-TYPICAL FORWARD CHARACTERISTICS

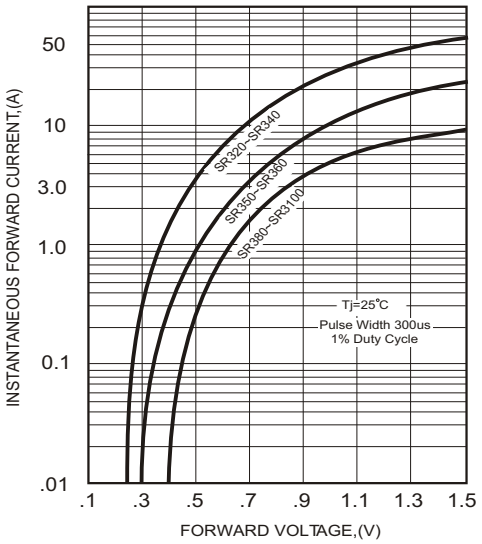


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

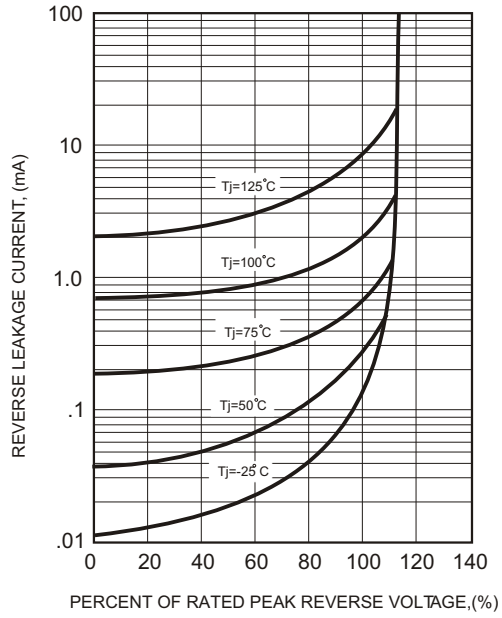


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

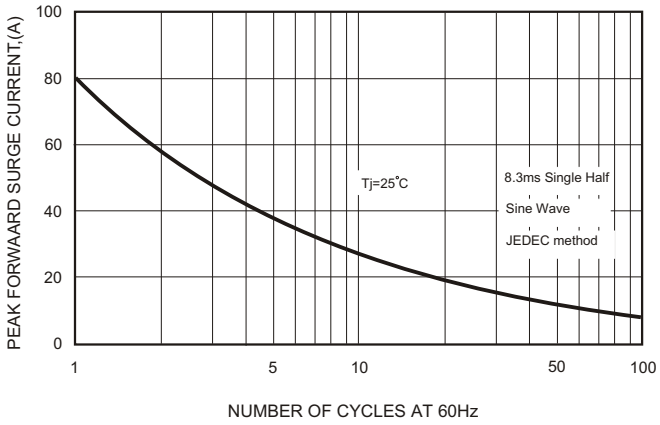
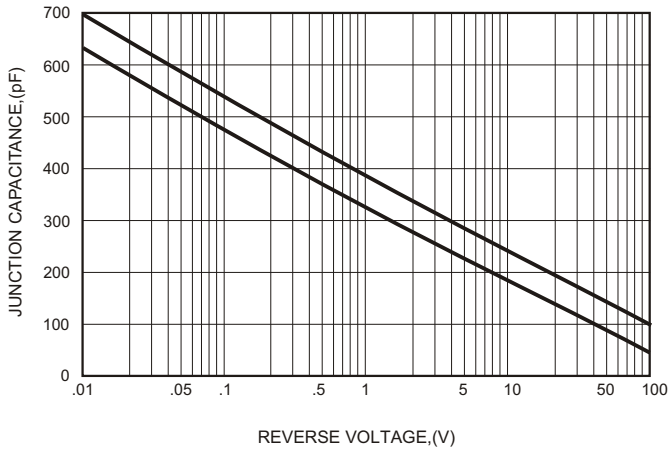


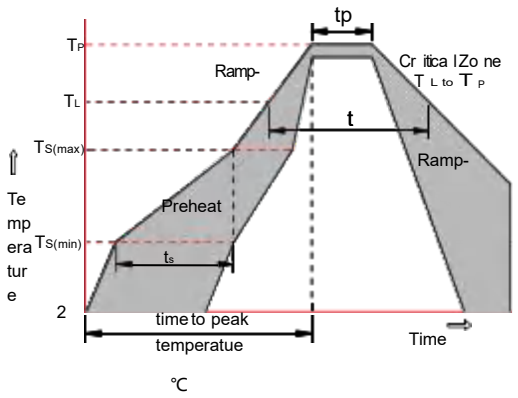
FIG.5-TYPICAL JUNCTION CAPACITANCE



Soldering parameters

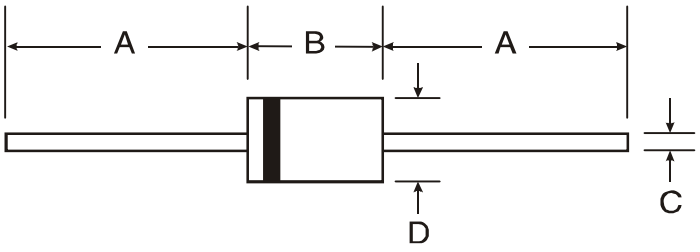
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition



Package Dimensions & Suggested Pad Layout

DO-27



DO-27		
Dim	**Min**	**Max**
A	24.00	-
B	7.20	9.50
C	1.15	1.25
D	5.00	5.60
All Dimensions in mm		